Interim Results Announcement
The information contained in this presentation is provided for informational purpose only, and should not be relied upon for the purpose of making any investment or for any other purpose. Some of the information used in preparing this presentation was obtained from third parties or public sources. The information contained in this presentation has not been independently verified. No representation or warranty, expressed or implied, is made as to, and no reliance should be placed on, the fairness, reasonableness, accuracy, completeness or correctness of such information or opinions contained herein. It is not the intention to provide, and you may not rely on this presentation as providing, a complete or comprehensive analysis of our financial or trading position or prospects. The information and opinions contained in this presentation are provided as at the date of this presentation and are subject to change without notice and will not be updated to reflect any developments which may occur after the date of this presentation.

All statements, other than statements of historical facts included in this presentation, are or may be forward-looking statements. Forward-looking statements include, but are not limited to, those using words such as “seek”, “expect”, “anticipate”, “estimate”, “believe”, “intend”, “project”, “plan”, “strategy”, “forecast” and similar expressions or future or conditional verbs such as “will”, “would”, “should”, “could”, “may” and “might”. These forward-looking statements reflect the Company’s current expectations, beliefs, hopes, intentions or strategies regarding the future and assumptions in light of currently available information. Such forward-looking statements are not guarantees of future performance or events and involve known or unknown risks and uncertainties. Accordingly, actual results may differ materially from information contained in the forward-looking statements as a result of a number of factors. You should not place undue reliance on such forward-looking statements, and the Company does not undertake any obligation to update publicly or revise any forward-looking statements. No statement in this presentation is intended to be or may be construed as a profit forecast.

We also do not undertake any obligation to provide you with access to any additional information or to update this presentation or any additional information or to correct any inaccuracies in this presentation or any additional information which may become apparent.

This presentation does not constitute an offer or invitation to purchase or subscribe for any shares and no part of it shall form the basis of or be relied upon in connection with any contract, commitment or investment decision in relation thereto.
Awards & Accolades

Forbes Asia 2019
BEST OVER A BILLION

2019 HKMA Quality Award

2019 WINNER

Winner of the productronica innovation award 2019

Asia Money 2019

ASME Pacific Technology
The World’s Technology & Market Leader

Q2 2020 Group Revenue: USD 557m

Semiconductor Solutions 50.1%
SMT Solutions 36.6%
Materials 13.3%
ASMPT’S
Major Facilities
Around The World

- Sales Offices
- Business Centre / R&D / Manufacturing Site

- >2,000 Global R&D staff
- >1,400 Patents on leading edge technologies
- 10 R&D centres worldwide
- 12 Manufacturing facilities

locations:
- Boston
- Porto
- Munich
- Regensburg
- Weymouth
- Beuningen
- Fuyong (福永)
- Huizhou (惠州)
- Longgang (龙岗)
- Taoyuan
- Chengdu (成都)
- Johor
- Singapore
- Hong Kong

OVERVIEW
Three Business Segments With Leading Market Positions

SEMICONDUCTOR SOLUTIONS

#1 in Assembly & Packaging Equipment Market

Since 2002

2019 Worldwide PAE Market Share:

~29%

SMT SOLUTIONS

#2 in SMT Equipment Market

2019 Worldwide SMT Market Share:

~22%

MATERIALS

#3 in Leadframe Market

2018 Worldwide Leadframe Market Share:

~9%

Sources: VLSI, SEMI and ASMPT Market Intelligence | Formerly Backend Equipment Solutions
Our Strategic Value-added Acquisitions

<table>
<thead>
<tr>
<th>Advanced Packaging</th>
<th>Silicon Photonics</th>
<th>Manufacturing Execution Software</th>
</tr>
</thead>
<tbody>
<tr>
<td>• Largest installed base of panel deposition tools</td>
<td>• Ultra high precision sub-micron die attach equipment solutions</td>
<td>• Provider of automation and manufacturing software for high-tech industries</td>
</tr>
<tr>
<td>• Addition to the Advanced Packaging suite of solutions</td>
<td>• In prime position to capture demand for future data centre bandwidth growth and next generation 5G deployments</td>
<td>• Capture demand for SMART Factory software solutions</td>
</tr>
<tr>
<td>• High Performance Computing (HPC)</td>
<td></td>
<td>• Well-established MES solutions provider with a strong presence in China.</td>
</tr>
</tbody>
</table>

- Complements Critical Manufacturing MES solutions, reinforcing ASMPT’s position in the China market.
Our Participation in Emerging and Disruptive Technologies

### Minority Investments in Start-ups
- **X-ray Inspection**
  - X-ray inspection of advanced semiconductor packages
  - Up to 100X faster vs conventional X-ray using proprietary technology
- **3D Laser Printing**
  - Israeli company with cutting-edge technology
  - Potentially disruptive technology to the SMT printing industry

### Strategic Collaborations
- **Data Analytics**
  - Industrial IoT Solutions to deliver holistic data analytics solutions
  - Provide customer value through productivity, quality and reliability in manufacturing operations
- **AI Chip Technology**
  - Development of Heterogeneous Integration (HI) to advance packaging technologies and tools
# Q2/1H 2020 Billings

<table>
<thead>
<tr>
<th></th>
<th>Q2</th>
<th>1H</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
<td>QoQ</td>
</tr>
<tr>
<td>Group</td>
<td>557m</td>
<td>+27.8%</td>
</tr>
<tr>
<td>Semi Solutions</td>
<td>279m</td>
<td>+43.0%</td>
</tr>
<tr>
<td>Materials</td>
<td>74m</td>
<td>+43.2%</td>
</tr>
<tr>
<td>SMT Solutions</td>
<td>204m</td>
<td>+8.0%</td>
</tr>
</tbody>
</table>

**Q 2 2020 HIGHLIGHTS**

- 1H Group Billings ~US$1B
  - ▲ 5.9% YoY ▼ 10.5% HoH
- Q2 Group Billings
  - ▲ 19.5% YoY ▲ 27.8% QoQ

**SEMI**

Key drivers for Q2 YoY billings growth
- Advanced Packaging
  - NEXX delivered strong growth
- Other drivers: Optoelectronics and IC/Discrete
- Traditional wire/die bonders delivered relatively strong growth
- CIS billings relatively weaker due to soft smartphone market demand

**SMT**

- Driven by 5G & SiP applications
Q2 2020 Billings – Business Segments

QoQ Growth:
+43.0%

QoQ Growth:
+8.0%

QoQ Growth:
+43.2%

Semiconductor Solutions (USD'M)

SMT (USD'M)

Materials (USD'M)

QoQ Growth:
+8.0%
## Q2/1H 2020 Group Bookings

<table>
<thead>
<tr>
<th></th>
<th>Q2</th>
<th>1H</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
<td>QoQ</td>
</tr>
<tr>
<td><strong>Group</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>472m</td>
<td>-29.4%</td>
</tr>
<tr>
<td><strong>Semi Solutions Segment</strong></td>
<td>227m</td>
<td>-26.7%</td>
</tr>
<tr>
<td><strong>Materials Segment</strong></td>
<td>78m</td>
<td>-11.8%</td>
</tr>
<tr>
<td><strong>SMT Solutions Segment</strong></td>
<td>167m</td>
<td>-38.4%</td>
</tr>
</tbody>
</table>

### Group
- 1H Bookings ▲ HoH and YoY
- Q2 Bookings ▼ QoQ and YoY as a result of overall weak sentiment due to COVID-19

### SEMI
- Q2 Bookings ▼ QoQ due to higher Q1 base
- Key drivers of Q2 Bookings
  - Advanced Packaging
  - Optoelectronics and IC/Discrete
- Q2 Bookings for CIS relatively weaker due to soft smartphone market

### SMT
- Key driver of Q2 Bookings
  - 5G-related investments in China
  - SiP
- Q2 Bookings in Automotive and Industrial Applications were weak

### Materials
- Q2 Bookings at high level despite decline QoQ after 5 consecutive quarters’ growth
Q2 2020 Bookings – Business Segments

**QoQ Growth:**
- **Semiconductor Solutions (USD'M):** -26.7%
- **SMT (USD'M):** -38.4%
- **Materials (USD'M):** -11.8%
### Q2/1H 2020 Group GM & Profitability

<table>
<thead>
<tr>
<th>Gross Margin</th>
<th>1H</th>
<th>HoH</th>
<th>YoY</th>
<th>Q2</th>
<th>QoQ</th>
<th>YoY</th>
</tr>
</thead>
<tbody>
<tr>
<td>Group</td>
<td>34.5%</td>
<td>-29 bps</td>
<td>-34 bps</td>
<td>35.2%</td>
<td>+169 bps</td>
<td>-54 bps</td>
</tr>
<tr>
<td>Semi Solutions Segment</td>
<td>42.2%</td>
<td>+16 bps</td>
<td>+219 bps</td>
<td>42.9%</td>
<td>+162 bps</td>
<td>+211 bps</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>13.5%</td>
<td>+409 bps</td>
<td>+250 bps</td>
<td>16.9%</td>
<td>+838 bps</td>
<td>+546 bps</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>31.8%</td>
<td>-225 bps</td>
<td>-409 bps</td>
<td>31.3%</td>
<td>-101 bps</td>
<td>-616 bps</td>
</tr>
</tbody>
</table>

**Group**
- Q2 Group GM close to mid-point of guidance
- Q2 Group Billing, Operating Profit and Net Profit ▲ QoQ and YoY

**SEMI**
- 1H GM ▲ YoY due to higher volume effect, increased productivity, product mix and cost reduction efforts

**SMT**
- 1H GM ▼ YoY due to lower contribution from Automotive and Industrial Applications; and larger China customer base

**Materials**
- 1H GM ▲ YoY due to higher volume effect and discontinuation of loss-making MIS business
Key Highlights:

Semiconductor Solutions Segment

- Strong global demand for HPC for datacentre and 5G applications
  - Q2 Billings growth YoY underpinned by Advanced Packaging
  - Q2 NEXX Bookings ▲ ~100% YoY
- Largest installed base to-date worldwide for Thermo-Compression Bonding (TCB) solutions
- NEXX has largest installation of panel plating tools for HPC applications
- Frontier-focused joint development with IBM Research on integrated solutions for HI, using ALSI Laser dicing, Hybrid Bonding and other AP interconnect tools
Key Highlights:

SMT Segment

- Market leader in System-in-Packaging (SiP)
- 1H booking momentum driven by
  - 5G-related investments
  - SiP – fast growing business within SMT
Key Highlights:

Materials Segment

- Segment new bookings increased five out of the last six quarters
- GM improvements resulted from higher volume effect and discontinuation of loss-making MIS business
- High level of Q2 Bookings indicates healthy demand for semiconductor devices
- Strategic JV expected to bring Materials Business to greater heights
R&D Commitment Makes Us a Preferred Partner of Choice

USD1,742 million invested in R&D

1H 2020 R&D expenditure

- US$ 101 million
- 11.7% of Equipment Sales

Package Interconnection
Optics precision engineering
Vibration control
Laser dicing & grooving
SMT
An Extensive Customer Base

- No single customer accounted for more than 10% of Group revenue
- Top 5 customers accounted for 16.25% of Group’s 1H 2020 revenue
- Top 20 customers include:
  - World’s leading Telecommunication and Information Technology provider
  - Leading High-Density Substrate makers
  - World’s leading IDMs
  - Tier 1 OSATs, major OSATs in China
  - Major camera module makers
  - Top EMS providers
  - Leading automotive component suppliers
- Among Top 20 customers of Group:
  - 4 from SMT Solutions segment
  - 8 from both Semi Solutions & SMT Solutions segment
1H 2020 Revenue Breakdown by Application Markets

1H 2020 Billing by Market Application

More Resilient in a Downturn with Multiple Application Markets Strategy
1H2020 Dividends

Dividends Per Share (HKD) & Dividend Payout Ratio

- Adopting a prudent stance in light of COVID-19 outbreak situation
- Dividend of HKD 0.70 for 1H20, representing a payout ratio of 74% for 1H20
New Lifestyle Norms

Fast-tracking Digitalisation

“Zoom, Microsoft Teams usage are rocketing”
Marketwatch, April 2020

“First-Quarter Demand Picked Up on Laptop Orders”
Intel

“Apple and Google partner on COVID-19 contact tracing technology”
Apple, Google, April 2020

‘Work from Home’ Initiatives by Companies Worldwide

Home-based Learning adopted by schools

Online “Live” Fitness Classes

Harnessing Technology in Contact Tracing
Data-Centric Era will spur Semiconductor Demand

Collect
Camera, 3D Sensing, Industry IoT, Sensor, LIDAR

Transmit
5G, WiFi, LiFi

Store
Big Data Centre, Cloud Computing, Memory

Analyse
AI, TPU, Data Analytics, HPC

Visualise
AR, VR, Micro LED, Mini LED

ASMPT's Enabling Solutions
- CMOS Imaging Sensors
- Active Alignment
- Precision Die Attach

- Silicon Photonics
- RF Filters
- Wire Bonding
- SAW Filters
- BAW Filters
- SMT Solutions
- PVD

- Silicon Photonics
- TCB
- Wire Bonding
- PLFO
- Laser Dicing

- WLFO
- PLFO
- Pick & Place
- Laser Grooving
- TCB
- PVD/ECD
- Precision Die Attach
- Heterogeneous Integration

- High Precision Die Attach
- Mini/Micro LED Displays
Q2 2020 Growth Drivers For ASMPT
Digital Acceleration Opportunities in China

Source: Trendforce and Nikkei Asian Review reporting

China’s investment in 5G infrastructure

Investment (In billions of yuan)

<table>
<thead>
<tr>
<th>Year</th>
<th>China Mobile</th>
<th>China Telecom</th>
<th>China Unicom</th>
</tr>
</thead>
<tbody>
<tr>
<td>2019</td>
<td>250,000</td>
<td>140,000</td>
<td>110,000</td>
</tr>
<tr>
<td>'20</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Planned number of base stations*

* Source: Trendforce and Nikkei Asian Review reporting
"Power" Up All Industries

Base Stations

2019-2025: 25-30mil New 5G

Source: Topology Research Institute 2019

Big Data Cloud Servers

2023: 417mil New 5G Handsets

Source: IDC, 2019

Smart Consumer

“Power” Up All Industries

50 MEMS & Sensors per car

Automotive

Source: Bosch, 2019

5G Will Transform the World Beyond Our Imagination

5G

Infrastructure

Terminal

ASMPT Solutions for 5G:

IC & Discrete Solutions

Photonics Solutions

Power Solutions

Image Sensor Solutions

Advanced Packaging

SMT Solutions

Wafer Separation

Smart Consumer

Big Data Cloud Servers

“Power” Up All Industries

50 MEMS & Sensors per car

Automotive

Base Stations

2019-2025: 25-30mil New 5G

Source: Topology Research Institute 2019

2023: 417mil New 5G Handsets

Source: IDC, 2019

Source: Bosch, 2019
Complete CIS Camera Assembly Solution

Market Leader for Unique In-line Solutions

IDEALine™
(CMOS Image Sensor Solution)

ACamLine™
(Automotive Camera Assembly Solution)

AUTOPIA FT
(Automatic Camera Testing System)

Smartphone Solutions

Automotive Solutions

ASMPacific Technology
Advanced Packaging Enables Heterogeneous Integration

End Applications:

- **AUTOMOTIVE**
  - Sensors, Camera, Body Electronics, Safety Systems, Infotainment

- **DATACENTRES**
  - for HPC, Machine Learning

- **IoT ERA**
  - Smart Wearables & Smart Machines (Factories)

- **GPU**
  - for VR/AR & AI

- **NEXX**
  - PVD | ECD Bumping, TSV & RDL

- **LASER 1205**
  - Laser Separation Wafer Dicing & Grooving

- **SIPLACE CA**
  - Die Attach & SMT Wafer & Panel Recon IPD tool

- **NUCLEUS XPM**
  - HBM Bonder

- **NUCLEUS**
  - Pick & Place Wafer & Panel Level

- **FIREBIRD**
  - TCB, FLI

- **ORCAS**
  - Compression mold Wafer & Panel Level

**Advanced Packaging Enables Heterogeneous Integration**
Hybrid Bonding Solution
Next Generation Heterogeneous Integration Technology

Bringing Heterogeneous Integration to the next level to enable high performance device, driving for future AI & HPC technology in a more cost effective way

- **Higher Interconnect density**
  Interconnect density > $10^5$/mm², with connecting pad size and pitch down below 5um

- **Zero bond line with bump-less interconnect**
  With direct Cu-Cu hybrid bonding

- **Better signal integrity and thermal performance**

ASM Advanced Packaging Technology enables Hybrid bonding solution for Heterogeneous Integration

- Ultra High Placement accuracy
  Bond accuracy +/- 200nm

- Ultra High Cleanliness

- High Productivity
  CPH > 2K

Source: Chipworks
Source: Chipworks
Source: Xperi
Source: Xperi
Future Growth Drivers for OPTO Business

**MiniLED**
Medium to Large RGB / BLU Display

- Market Size CAGR (2019 – 2025)
  - ~ 35%

**MicroLED**
Small Gadget & Transparent Display

- Market Size CAGR (2019 – 2025)
  - ~ 131%

**Fast Growing Applications**

- **Automotive Display CAGR (2019 – 2025)**
  - 63%

- **Digital Display CAGR (2019 – 2025)**
  - 35%

- **Large Display CAGR (2019 – 2025)**
  - 31%

- **Smartphone Display CAGR (2022 – 2025)**
  - 118%

- **Wearable Display CAGR (2020 – 2025)**
  - 91%

- **VR Display CAGR (2021 – 2025)**
  - 75%

**Source:** LEDInside, Sep 2019

**Source:** Photos of displays from various conferences

- **TCL**
  - (TCL Conference - 2019)

- **LEYARD**
  - (InfoComm - 2019)

- **RitDisplay + PlayNitride**
  - (Touch Taiwan - 2019)

- **TIANMA**
  - (SID - 2019)

- **CEDAR ELECTRONICS**
  - (InfoComm - 2019)

- **KONKA**
  - (KONKA Conference - 2019)

- **AUO**
  - (Touch Taiwan - 2019)

- **Samsung**
  - (CES - 2019)
Unique and Ready for Mass Production
Mini & Micro LED Solution

Mass Transfer
Up to 300,000 chips per bonding cycle
Booming Applications in Photonics Market

- Datacenter transceivers
- Long haul transceivers
- Optical interconnects
- Automotive LiDAR
- Immunoassay tests
- Fiber-optic gyroscope
- 5G transceivers

2019
$480M

$117M
$364M
$18M
$20M
$22M
$44M
$61M

$3.6B
CAGR 46%

$186M
CAGR 8%

2025
$3.9B

Si Photonics Market Size (USD'M)

Source: Yole, 2020
IIoT & Smart Manufacturing
Powered Up by 5G Network

Factory in Location A
Factory in Location C
Factory in Location B
Factory in Location D

Industrial IoT

\[ \sim 24\% \]

CAGR (2019 – 2023)
Source: Marketwatch, Sep 2019
Digital Technologies Enabling the Autonomous Driving Experience

- 5G NETWORK
- MEMS
- POWER
- DISPLAY
Outlook
Outlook

- Global full year 2020 growth projections revised downwards from -3.0% to -4.9% by IMF during June 2020 review.
- Threat from a second wave of COVID-19 infection and continued fallout from the worsening US-China tension remains a global concern for 2H2020.
- In light of these uncertainties, no guidance on Q3 Bookings will be provided.

Q3 Group Billings Guidance
- US$480m – US$560m
- Subdued demand for Automotive and weakness in Eurozone

Longer Term Outlook
- Supply chain localization and deployment of 5G infrastructure opening up new market opportunities in:
  - AP, Silicon Photonics, IIoT, mini and micro LED solutions, Power semiconductor and Industry 4.0
Industry Growth Forecast (2020)

Semiconductor Industry Forecast Global Assembly & Packaging Equipment Market

- **Gartner, Apr-20**: -0.9%
- **Omdia, Apr-20**: 2.5%
- **IDC, May-20**: -4.2%
- **Cowan LRA Model, May-20**: 7.6%
- **Semiconductor Intelligence, May-20**: -6.0%
- **WSTS, Jun-20**: 3.3%

- **VLSI Assembly & Packaging Equipment (Jun-20)**: -22%, 22%, -16%, 13%, 26%, -3%, -32%, 11%
- **SEMI Assembly & Packaging Equipment (Jul-20)**: -26%, 33%, -18%, 20%, 26%, 1.9%, -27%, 10%

Note: Data as of July 2020

Source:
- Semiconductor Intelligence, May-20
- Cowan LRA Model, May-20
- IDC, May-20
- Omdia, Apr-20
- Gartner, Apr-20
- WSTS, Jun-20
- Omdia, Apr-20
Recent Awards & Recognition

**Awards & Recognition**

**Latest**

**Large**

1. **ADVANTEST**
   - Rating: 9.56
   - Stars: ★★★★★

2. **TERADYNE**
   - Rating: 9.40
   - Stars: ★★★★★

3. **ASML**
   - Rating: 9.31
   - Stars: ★★★★★

4. **ASM Pacific Technology**
   - Rating: 8.82
   - Stars: ★★★★★

5. **KE**
   - Rating: 8.34
   - Stars: ★★★★★

6. **TEL**
   - Rating: 8.21
   - Stars: ★★★★★

7. **Lam Research**
   - Rating: 8.00
   - Stars: ★★★★★

8. **Hitachi High-Tech**
   - Rating: 7.04
   - Stars: ★★★★★

**Focused**

1. **Plasma-Therm**
   - Rating: 9.02
   - Stars: ★★★★★

2. **FormFactor**
   - Rating: 8.81
   - Stars: ★★★★★

3. **EUV**
   - Rating: 8.56
   - Stars: ★★★★★

4. **Cohu**
   - Rating: 8.21
   - Stars: ★★★★★

5. **axcelis**
   - Rating: 7.91
   - Stars: ★★★★★

6. **Canon**
   - Rating: 7.75
   - Stars: ★★★★★

7. **Nikon**
   - Rating: 7.25
   - Stars: ★★★★★

These awards are presented for public release by VLSI Research and must be reprinted for a separate, clearly identifying the VLSI Research 2019 Customer Satisfaction Survey as the source. No advertising or other promotional use can be made of the information in this release, or VLSI Research's 2019 Customer Satisfaction Survey. Copyright © 2019 VLSI Research Inc. All rights reserved.
Q2/1H 2020
Financial Highlights
### Q2/1H 2020 Group Bookings

**QoQ Growth:**
-29.4%

---

#### Quarterly Group Bookings (USD‘M)

<table>
<thead>
<tr>
<th>Quarter</th>
<th>Q1 14</th>
<th>Q2 15</th>
<th>Q3 16</th>
<th>Q4 17</th>
<th>Q1 19</th>
<th>Q2 20</th>
</tr>
</thead>
<tbody>
<tr>
<td>Q1 14</td>
<td>472m</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Q2 15</td>
<td></td>
<td>537m</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Q3 16</td>
<td></td>
<td></td>
<td>167m</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Q4 17</td>
<td></td>
<td></td>
<td></td>
<td>437m</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Q1 19</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>1,141m</td>
<td></td>
</tr>
<tr>
<td>Q2 20</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>1,141m</td>
</tr>
</tbody>
</table>

#### Financial Review

<table>
<thead>
<tr>
<th></th>
<th>Q2 2020 Bookings</th>
<th>1H 2020 Bookings</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
<td>YoY</td>
</tr>
<tr>
<td>Group</td>
<td>472m</td>
<td>-21.6%</td>
</tr>
<tr>
<td>Semi Solutions Segment</td>
<td>227m</td>
<td>-8.1%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>78m</td>
<td>+32.7%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>167m</td>
<td>-43.7%</td>
</tr>
</tbody>
</table>
# Q2/1H 2020 Group Billings

**QoQ Growth:**
+27.8%

<table>
<thead>
<tr>
<th>Segment</th>
<th>Q2 2020 Billings</th>
<th>1H 2020 Billings</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
<td>YoY</td>
</tr>
<tr>
<td>Group</td>
<td>557m</td>
<td>+19.5%</td>
</tr>
<tr>
<td>Semi Solutions Segment</td>
<td>279m</td>
<td>+33.8%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>74m</td>
<td>+28.2%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>204m</td>
<td>+2.2%</td>
</tr>
</tbody>
</table>

**Quarterly Group Billings (USD'M)**
<table>
<thead>
<tr>
<th></th>
<th>Q2 2020</th>
<th>Q2 2020</th>
<th>1H 2020</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>YoY</td>
<td>QoQ</td>
<td>YoY</td>
</tr>
<tr>
<td>Bookings (USD)</td>
<td>472m</td>
<td>-21.6%</td>
<td>1,141m</td>
</tr>
<tr>
<td></td>
<td></td>
<td>-29.4%</td>
<td>+7.4%</td>
</tr>
<tr>
<td>Revenue (USD)</td>
<td>557m</td>
<td>+19.5%</td>
<td>992m</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+27.8%</td>
<td>+5.9%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>35.2%</td>
<td>-54 bps</td>
<td>34.5%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+169 bps</td>
<td>-34 bps</td>
</tr>
<tr>
<td>EBIT (HKD)</td>
<td>457m</td>
<td>+107.4%</td>
<td>581m</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+269.6%</td>
<td>+20.0%</td>
</tr>
<tr>
<td>Net Profit (HKD)</td>
<td>365m</td>
<td>+421.8%</td>
<td>391m</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+1,341.5%</td>
<td>+119.2%</td>
</tr>
<tr>
<td>Net Profit Margin</td>
<td>8.5%</td>
<td>+652 bps</td>
<td>5.1%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+771 bps</td>
<td>+262 bps</td>
</tr>
</tbody>
</table>
Q2/1H 2020 Segment Results – Semiconductor Solutions

<table>
<thead>
<tr>
<th></th>
<th>Amount</th>
<th>YoY</th>
<th>QoQ</th>
<th>Amount</th>
<th>YoY</th>
<th>HoH</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Bookings (USD)</strong></td>
<td>227m</td>
<td>-8.1%</td>
<td>-26.7%</td>
<td>537m</td>
<td>+14.2%</td>
<td>+21.7%</td>
</tr>
<tr>
<td><strong>Billings (USD)</strong></td>
<td>279m</td>
<td>+33.8%</td>
<td>+43.0%</td>
<td>473m</td>
<td>+16.6%</td>
<td>-4.5%</td>
</tr>
<tr>
<td><strong>Gross Margin</strong></td>
<td>42.9%</td>
<td>+211 bps</td>
<td>+162 bps</td>
<td>42.2%</td>
<td>+219 bps</td>
<td>+16 bps</td>
</tr>
<tr>
<td><strong>Segment Profit (HKD)</strong></td>
<td>336m</td>
<td>+404.3%</td>
<td>+297.2%</td>
<td>420m</td>
<td>+251.8%</td>
<td>+17.6%</td>
</tr>
<tr>
<td><strong>Segment Profit Margin</strong></td>
<td>15.5%</td>
<td>+1,140 bps</td>
<td>+993 bps</td>
<td>11.4%</td>
<td>+764 bps</td>
<td>+215 bps</td>
</tr>
</tbody>
</table>
# Q2/1H 2020 Segment Results – Materials

- **Bookings (USD)**
  - Q2 2020: 78m, +32.7% YoY, -11.8% QoQ
  - 1H 2020: 167m, +59.3% YoY, +25.2% HoH

- **Billings (USD)**
  - Q2 2020: 74m, +28.2% YoY, +43.2% QoQ
  - 1H 2020: 126m, +15.6% YoY, -3.2% HoH

- **Gross Margin**
  - Q2 2020: 16.9%, +546 bps, +838 bps
  - 1H 2020: 13.5%, +250 bps, +409 bps

- **Segment Profit (HKD)**
  - Q2 2020: 58m, +193.7% YoY, +266.6% QoQ
  - 1H 2020: 74m, +144.4% YoY, +163.4% HoH

- **Segment Profit Margin**
  - Q2 2020: 10.1%, +569 bps, +616 bps
  - 1H 2020: 7.6%, +399 bps, +479 bps
Q2/1H 2020 Segment Results – SMT Solutions

<table>
<thead>
<tr>
<th></th>
<th>Q2 2020</th>
<th>1H 2020</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Amount</td>
<td>YoY</td>
</tr>
<tr>
<td>Bookings (USD)</td>
<td>167m</td>
<td>-43.7%</td>
</tr>
<tr>
<td>Billings (USD)</td>
<td>204m</td>
<td>+2.2%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>31.3%</td>
<td>-616 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>159m</td>
<td>-24.0%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>10.0%</td>
<td>-346 bps</td>
</tr>
</tbody>
</table>
Free Cash Flow and Capital Investment

**Free Cash Flow (HK$ m)**

- 2013: 418
- 2014: 1,108
- 2015: 605
- 2016: 1,604
- 2017: 437
- 2018: 806
- 2019: 2,116
- 1H 2020: 1,095

**Capital Investment (US$ m)**

- 2015: 72
- 2016: 55
- 2017: 82
- 2018: 104
- 2019: 88
- 2019B: 90
- 1H 2020: 15
- 2020B: 82
- 2020E: 80

Note: D&A (excl. ROU/lease assets)
Financial Metrics

Return on Invested Capital (ROIC)

Return on Equity (ROE)
ASM Pacific Technology

ENABLING THE DIGITAL WORLD